5. The method according to any one of claims 1 to 4, wherein the pattern includes an arrangement of gold applied to the portion of the pin used for electrical connectivity.

6. The method according to any one of claims 1 to 4, wherein the pattern includes an arrangement so as to impart information to an observer.

7. The method according to claim 6, wherein the information includes any one or a combination of pin manufacturer, manufacturing date, material and/or physical properties of the gold plating.

~~8. A method for plating a leadframe, the method comprising the steps of:~~

~~providing said leadframe;~~

~~applying a dry film lamination to said leadframe;~~

~~exposing said leadframe so as to impart an image to said dry film~~

~~applying a metallic plating to said exposed image such that the thickness of said metallic plating is less than the thickness of the dry film lamination.~~

~~9. The method according to claim 8, further including the steps, after the metallic plating step, of placing target marks on said lead frame and then exposing the leadframe, such that the target marks ensure alignment of the leadframe during the exposing step.~~

~~10. The method according to claim 8 or 9, further including the steps of etching the~~ dry film lamination from the leadframe and filtering etchant to remove dry film particles.

11. The method according to any one of claims 8 to 10, wherein the metallic plating is silver and further including the step, after the metallic plating step, of ~~chamfering an edge of said plating.~~